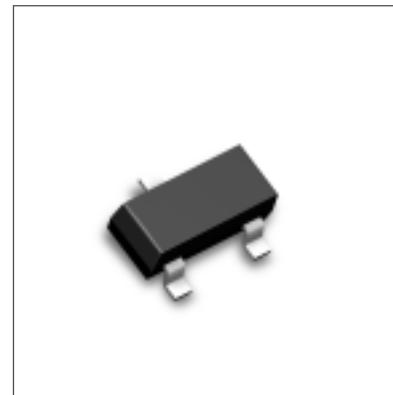
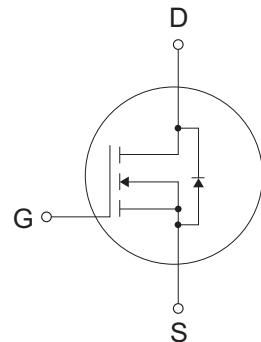


N-CHANNEL ENHANCEMENT MODE FIELD EFFECT TRANSISTOR**VOLTAGE** | 60 Volts**CURRENT** | 115 mAmp**PACKAGE****SOT-23****DESCRIPTION**

- N-channel enhancement mode field effect transistor, designed for high speed pulsed amplifier and driver applications, which is manufactured by the N-Channel DMOS process.

**FEATURES**

- High density cell design for low $R_{DS(on)}$.
- Voltage controlled small signal switching.
- Rugged and reliable.
- High saturation current capability.
- High-speed switching.
- CMOS logic compatible input.
- Not thermal runaway.
- No secondary breakdown.

**ABSOLUTE MAXIMUM RATINGS**

TA = 25°C Unless otherwise noted.

Parameter	Symbol	2N7002	Units
Drain-Source Voltage	V _{DSS}	60	V
Drain-Gate Voltage ($R_{GS} \leq 1M\Omega$)	V _{DRG}	60	V
Gate Source Voltage -Continuous -No Repetitive ($t_p < 50\mu s$)	V _{GSS}	± 20 ± 20	V
Maximum Drain Current -Continuous -Pulsed	I _D	115 800	mA
Maximum Power Dissipation Derated Above 25°C	P _D	200	mW
Operation and Storage Temperature Range	T _J , T _{STG}	-55 to +150	mW / °C
Thermal Resistance, Junction-to-Ambient	R _{θJA}	625	°C / W

ELECTRICAL CHARACTERISTICS

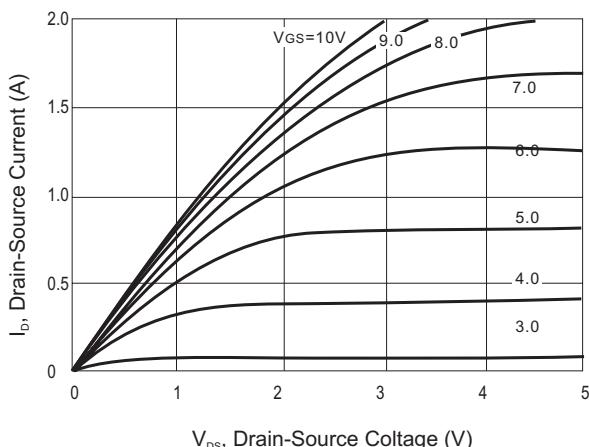
TA = 25°C Unless otherwise noted.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =10μA	60	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V, T _J =25°C V _{DS} =60V, V _{GS} =0V, T _J =125°C	-	-	1.0 0.5	μA mA
Gate - Body Leakage, Forward	I _{GSSF}	V _{DS} =0V, V _{GS} =20V	-	-	100	nA
Gate - Body Leakage, Reverse	I _{GSSR}	V _{DS} =0V, V _{GS} = -20V	-	-	-100	nA
ON CHARACTERISTICS (note1)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	2.1	2.5	V
Static Drain-Source On-Resistance	R _{Ds(ON)}	V _{GS} =10V, I _D =500mA, T _J =100°C	-	1.2	7.5	Ω
Drain-Source On-Voltage	V _{Ds(ON)}	V _{GS} =10V, I _D =500mA V _{GS} =5.0V, I _D =50mA	- -	0.60 0.09	3.75 1.50	V
On-State Drain Current	I _{D(ON)}	V _{GS} =10V, V _{DS} ≥ 2V _{Ds(ON)}	500	2700	-	mA
Forward Transconductance	G _{Fs}	V _{DS} ≥ 2V _{Ds(ON)} , I _D =200mA	80	320	-	mS
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, F=1.0 MHz	-	20	50	pF
Output Capacitance	C _{oss}	V _{DS} =25V, V _{GS} =0V, F=1.0 MHz	-	11	25	pF
Reverse Transfer Capacitance	C _{rss}	V _{DS} =25V, V _{GS} =0V, F=1.0 MHz	-	4	5	pF
Turn-On Time	T _{ON}	V _{DD} =30V, R _L =150Ω, I _D =200 mA V _{GS} =10V, R _{GEN} =25Ω	-	-	20	ns
Turn-Off Time	T _{OFF}	V _{DD} =30V, R _L =150Ω, I _D =200 mA V _{GS} =10V, R _{GEN} =25Ω	-	-	20	ns

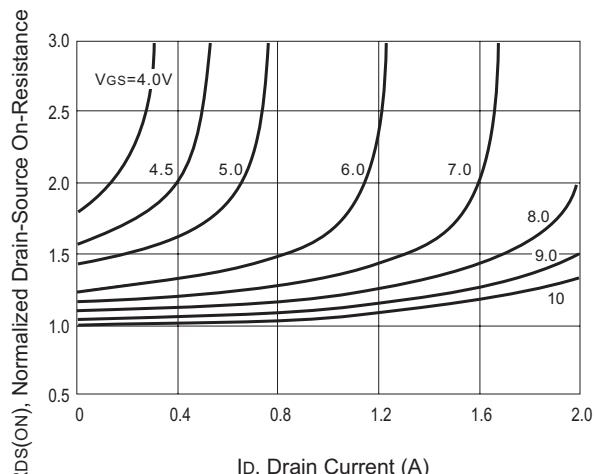
Note:

1.Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%

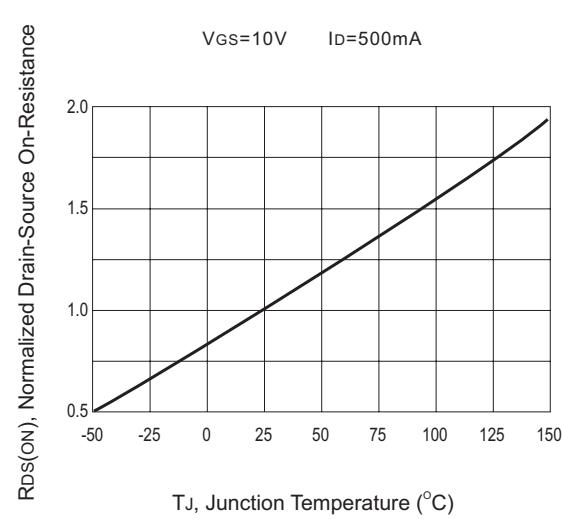
RATING and CHARACTERISTIC CURVES



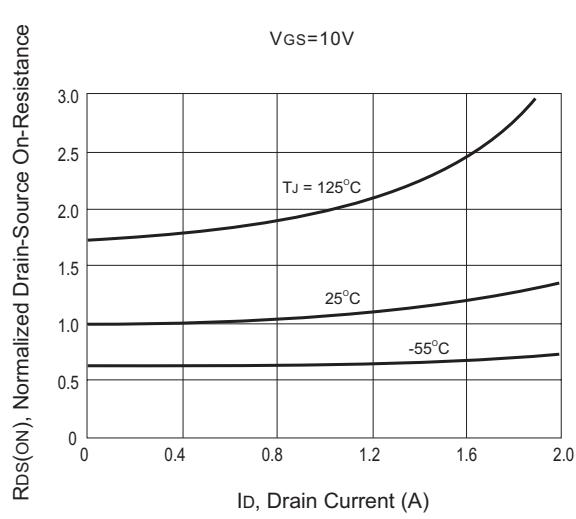
On-Region Characteristics



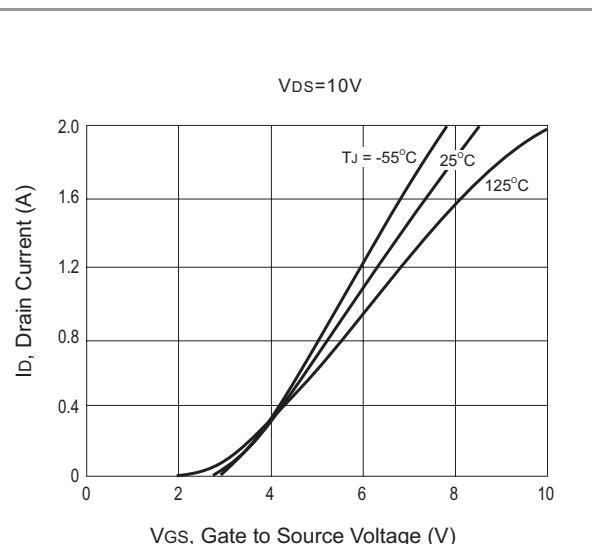
On-Resistance v.s. Gate Voltage and Drain Current



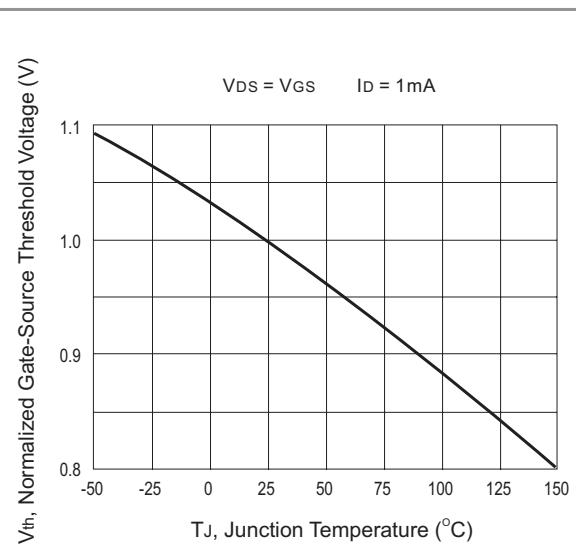
On-Resistance v.s. Temperature



On-Resistance v.s. Drain

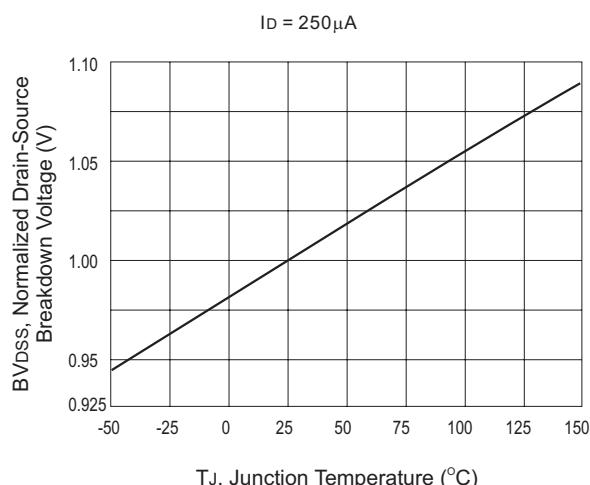


Transfer Characteristics

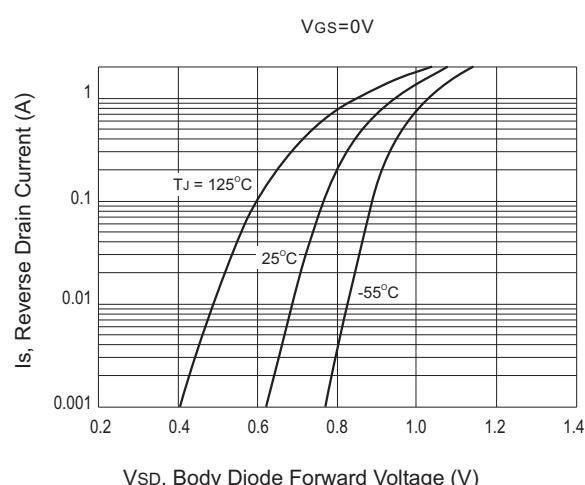


Gate Threshold v.s. Temperature

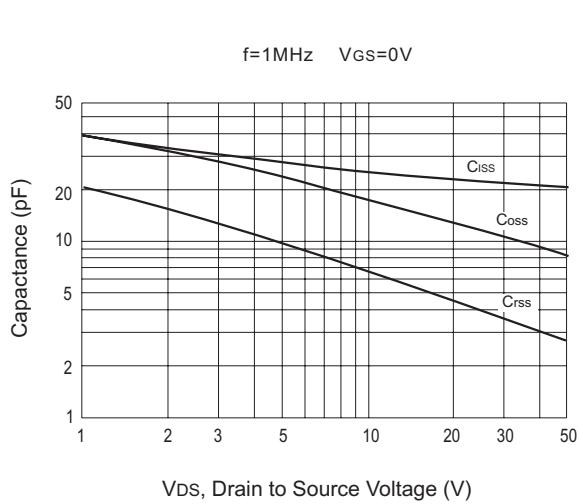
RATING and CHARACTERISTIC CURVES



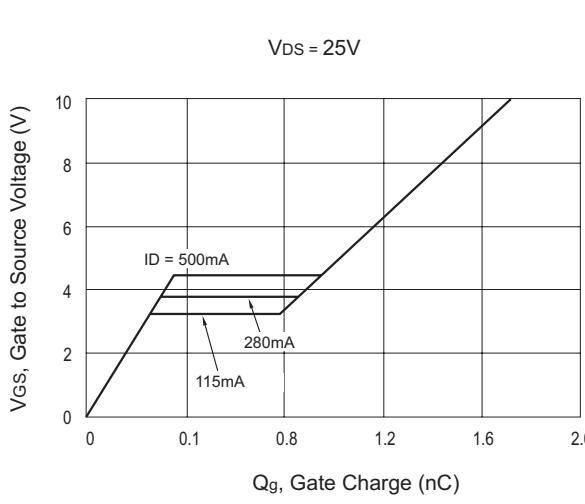
Breakdown Voltage v.s. Temperature



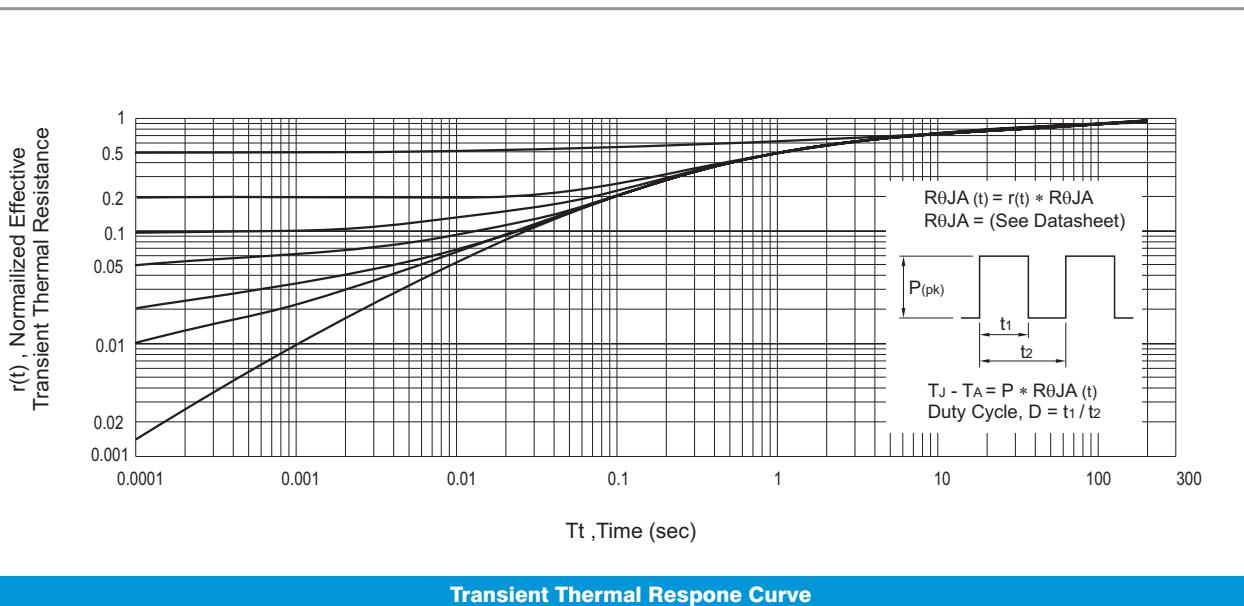
Body Diode Forward Voltage v.s. Current and Temperature



Capacitance Characteristics

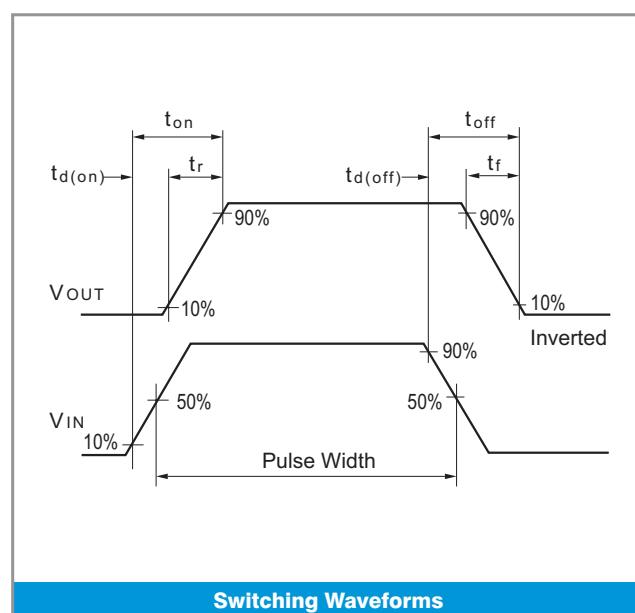
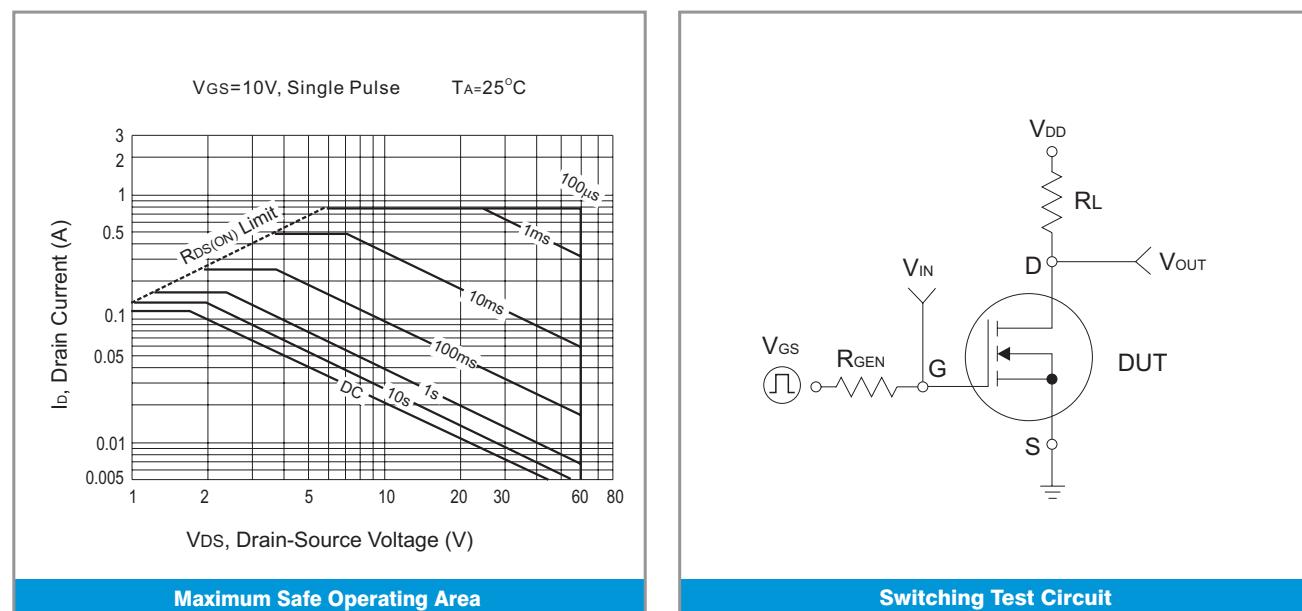


Gate Charge Characteristics



Transient Thermal Response Curve

RATING and CHARACTERISTIC CURVES



OUTLINE DRAWING

SOT-23

